





MXB1172A - Preliminary 10.7-12.75 GHz Bandpass Filter

Features

- Low Loss with High Rejection
- Low ripple

Applications

- Receive band for Ku-Band Satcom
- Specialty wireless applications



Materials: Ag plated ceramic block with fused-tin plated brass shield

Description

Surface mount ceramic bandpass filter. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared other bandpass filter technologies.

Electrical Specifications – specs are estimates based on simulation & subject to protoype verfication

Parameter	Frequency (GHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	2.0 Watt max
Peak Input Power	-	-	-	20 Watt max
Input-Output Response				
Passband Insertion Loss (500MHz avg)	10.70 - 12.75	1.3 dB	1.5 dB min	1.6 dB min
Passband Insertion Loss (single point)	10.70 - 12.75	1.4 dB	1.7 dB min	1.8 dB min
Passband Return Loss	10.70 - 12.75	11 dB	10 dB min	10 dB min
Attenuation:	1 - 9.70	47 dB	40 dB min	40 dB min
	13.75 - 13.99	39 dB	37 dB min	37 dB min
	14.00 - 16.50	43 dB	40 dB min	40 dB min
	16.51 - 17.00	35 dB	30 dB min	30 dB min

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

<u> Allowance</u>
0.1 dB
1.0 dB
1.0 dB

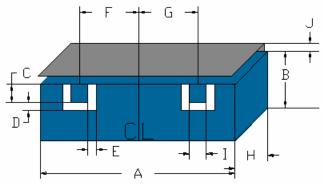
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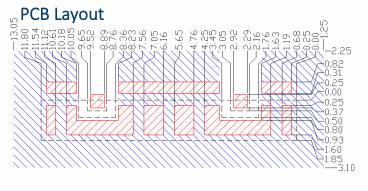


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Mechanical Drawing





Filter Solder Resist
Outline Dver Dielectric

Exposed Solder Resist
Conductor Dver Conductor

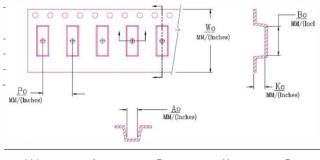
Dim.	Nominal (mm)	Tolerance (±mm or Max)	
Α	11.70	max	
В	1.50	max	
С	0.50	0.13	
D	0.30	0.13	
Е	0.40	0.13	
F	3.30	0.13	
G	3.30	0.13	
Н	3.70	max	
I	0.89	0.13	
J	0.63	0.20	

IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads <u>and</u> the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 4-6 mils of SAC305 with reflow incl. 120s of soak at 217°C, and up to 30 sec peak at 241°C.

Packaging and Marking



Wo	A_{o}	Bo	Ko	Po
0.945 in	0.098 in	0.366 in	0.132 in	0.315 in
24.0 mm	2.50 mm	9.30 mm	3.35 mm	8.0 mm

1 2 3 4 5 6 7 6 9 10 -10 -20 -30 -40 -50 -70 -85

Electrical Response

Frequency [MHz]

Marker 1 2 3 4 5 6 7 8 9 10

Freq[MHz] 9400 9700 10700 11200 11725 12250 12750 13750 14000 14500

S11[dB](1] -0.369 -0.298 -16.4 -15.9 -12 -15.6 -15.9 -0.599 -0.544 -0.515

S21[dB](1] -62.6 -53.1 -1.2 -1.22 -1.27 -0.982 -1.25 -39.7 -45.9 -50.3

12000

14000

15000

8000

10000

11000